

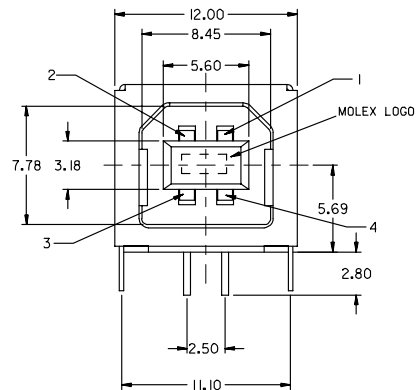
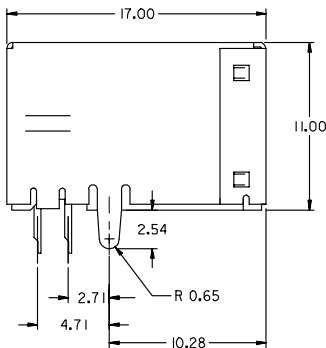
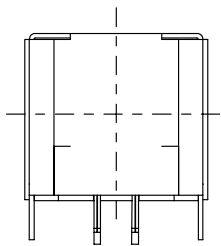
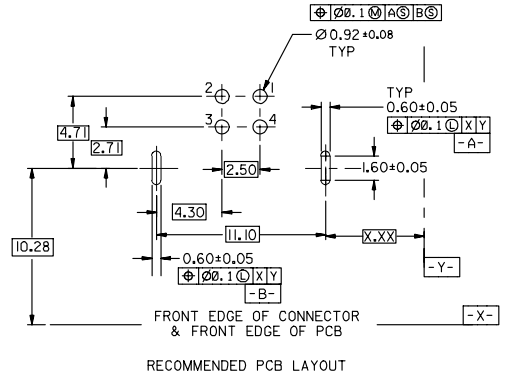
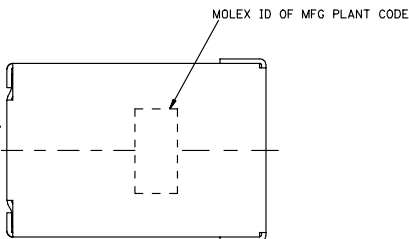


10 9 8 7 6 5 4 3 2 1

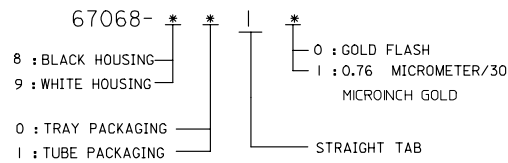
NOTES :  
 1. MATERIAL :  
 HOUSING : (a) HIGH TEMP. NYLON, CLASS FIBER FILLED, UL94V-0, COLOR: BLACK,  
 (b) POLYESTER, CLASS FIBER FILLED, UL94V-0, COLOR: WHITE,  
 TERMINAL : PHOSPHOR BRONZE  
 METAL SHELL : COPPER ALLOY

2. PLATING :  
 TERMINAL :  
 CONTACT AREA : (a) GOLD FLASH,  
 (b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM,  
 /0.76 MICROMETER MINIMUM.  
 SOLDER TAIL :  
 PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .  
 /1.9 MICROMETER MINIMUM.  
 UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM,  
 /1.27 MICROMETER MINIMUM.  
 METAL SHELL :  
 PURE TIN(Sn) THICKNESS= 50 MICROINCH MINIMUM,  
 /1.27 MICROMETER MINIMUM.  
 UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM,  
 /1.27 MICROMETER MINIMUM.

3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER  
 RECOMMENDED PCB THICKNESS : 1.60±0.05  
 4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000



PART NUMBER LEGEND:



NEW RELEASE EC NO. SH2005-0142 DRWN: DAVID HU 2004/11/05 CHKD: HARRY 2004/11/05 APPR: YITAP 2004/11/25	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
			mm	INCH	DRAWN BY DAVID HU	DATE 2004/11/05	TITLE USB B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE)	
		4 PLACES	±	---	CHECKED BY DAVID HU	DATE 2004/11/05		
		3 PLACES	±	---	APPROVED BY DAVID HU	DATE 2004/11/05		
		2 PLACES	±	0.25				
		1 PLACE	±	0.25				
		ANGULAR ± 3 °				MOLEX MOLEX INCORPORATED		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE NOTES		DOCUMENT NO. SD-67068-003	SHEET NO. 2	
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

9 8 7 6 5 4 3 2 1

8 7 6 5 4 3 2 1

NOTES :  
 1. MATERIAL :  
 HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,

TERMINAL : PHOSPHOR BRONZE  
 METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL :  
 CONTACT AREA : (a) GOLD FLASH,  
 (b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM,  
 /0.76 MICROMETER MINIMUM.

SOLDER TAIL :  
 PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM ,  
 /1.9 MICROMETER MINIMUM.

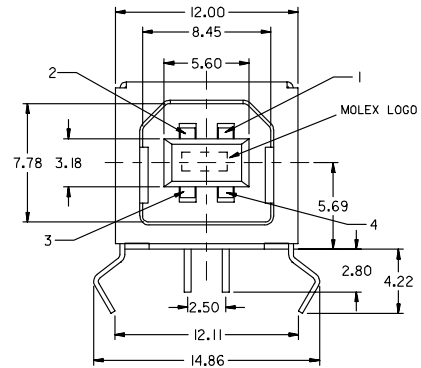
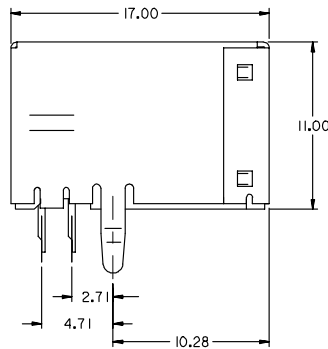
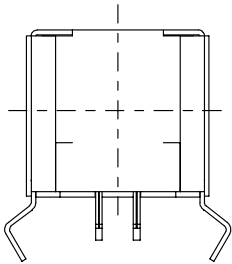
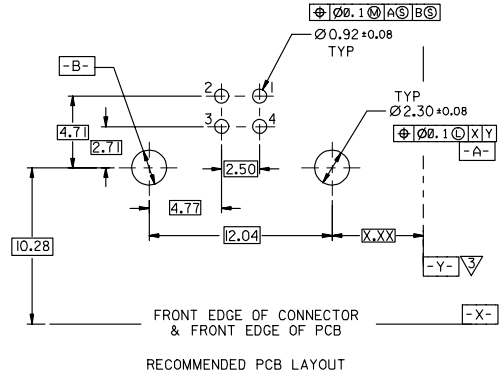
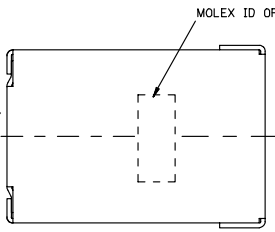
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM,  
 /1.27 MICROMETER MINIMUM.

METAL SHELL :  
 PURE TIN(Sn), THICKNESS= 50 MICROINCH MINIMUM,  
 /1.27 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM,  
 /1.27 MICROMETER MINIMUM.

▽ DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER  
 RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000



PART NUMBER LEGEND:

67068- 7041

				MATERIAL : SEE NOTES		MOLEX TAIWAN LTD.	
				FINISH : SEE NOTES		SHEET 3 OF 4	
				WIRE RANGE :		GENERAL TOLERANCES	
				INS. RANGE :		ANGLE : ± 3° DIM : ± .25/.010	
A NEW RELEASE FOR LEAD-FREE				DAVID HU 2004/11/5		ENG. NO.: SD-67068-003	
LTR REVISION RECORD ECN DR DATE				DRAWN BY 2004/11/5		REV A	
DAVID HU				CHK'D BY		TITLE : HIGH TEMP USB B TYPE CONNECTOR	
REVISION ONLY ON CAD SYSTEM				APPR'D BY		KINK TYPE BOARD LOCK (LEAD-FREE)	
				SCALE 4 : 1			

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX (FEM) AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

MXT, Sg - 13

ENG. NO.

EDP NO.

SIMILAR ITEM

CAD FILE :

DO NOT SCALE DRAWING

F

E

D

C

B

A

ENG. NO SDA-67068-0000

EDP NO.

SIMILAR ITEM

CAD FILE : \_S6706802\_

DO NOT SCALE DRAWING

8 7 6 5 4 3 2 1

NOTES :

1. MATERIAL :

HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,

TERMINAL : PHOSPHOR BRONZE  
METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL :  
CONTACT AREA : (a) GOLD FLASH,  
(b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM,  
/0.76 MICROMETER MINIMUM.

SOLDER TAIL :  
PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM,  
/1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM,  
/1.27 MICROMETER MINIMUM.

METAL SHELL :  
PURE TIN(Sn) THICKNESS= 50 MICROINCH MINIMUM,  
/1.27 MICROMETER MINIMUM.

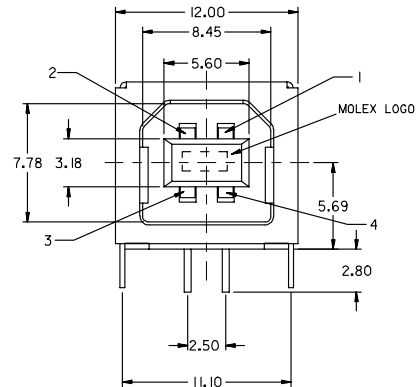
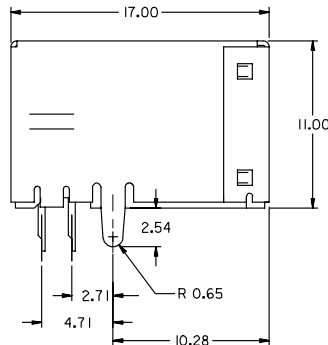
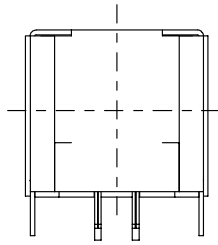
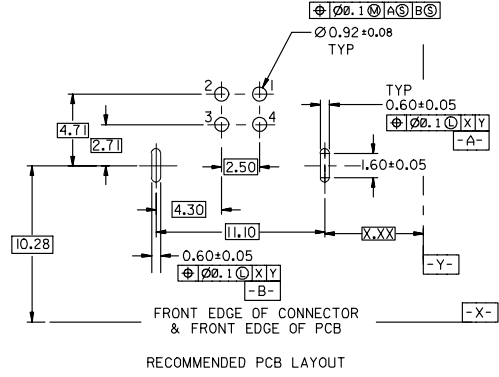
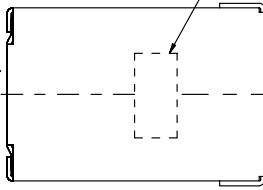
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM,  
/1.27 MICROMETER MINIMUM.

3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER

RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



PART NUMBER LEGEND:

67068- 7051

				MATERIAL : SEE NOTES		MOLEX TAIWAN LTD.	
				FINISH : SEE NOTES		SHEET 4 OF 4	
				WIRE RANGE :		GENERAL TOLERANCES	
				INS. RANGE :		ANGLE : ± 3° DIM : ± .25/.010	
A NEW RELEASE FOR LEAD-FREE				DAVID HJ 2006/11/5		ENG. NO.: SD-67068-003	
LTR REVISION RECORD ECN DR DATE				DRAWN BY 2004/11/5 DAVID HJ		REV A	
REVISE ONLY ON CAD SYSTEM				APPR'D BY		TITLE : HIGH TEMP/5B B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE)	
				SCALE 4 : 1			

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX (FEMLE) AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

MXT, Sg - 13